



Docket No.: M4065.0239/P239
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Larry Hillyer, et al.

Application No.: 09/653,561

Group Art Unit: 2812

Filed: August 31, 2000

Examiner: H. Nguyen

For: METHOD AND MATERIAL FOR
REMOVING ETCH RESIDUE FROM
HIGH ASPECT RATIO CONTACT
SURFACES

AMENDMENT UNDER 37 C.F.R. § 1.116

Box AF
Commissioner for Patents
Washington, DC 20231

Dear Sir:

In response to the Office Action dated February 12, 2003 (Paper No. 12), finally rejecting claims 1-4, 6-18, 20-31, 34-39, 41-44, 50, and 52-97, please amend the above-identified U.S. patent application as follows:

Please enter the amendment to the claims, beginning at page 2.

Please consider the Remarks, which begin at page 14.